

## N-Channel Lateral DMOS FETs

(Available Only In Extended Hi-Rel Flow)

### PRODUCT SUMMARY

Part Number	$V_{(BR)DS}$ Min (V)	$V_{GS(th)}$ Max (V)	$r_{DS(on)}$ Max ( $\Omega$ )	$C_{rss}$ Max (pF)	$t_{ON}$ Max (ns)
SD210DE-2	30	1.5	45 @ $V_{GS} = 10$ V	0.5	2
SD214DE-2	20	1.5	45 @ $V_{GS} = 10$ V	0.5	2

### FEATURES

- Ultra-High Speed Switching— $t_{ON}$ : 1 ns
- Ultra-Low Reverse Capacitance: 0.2 pF
- Low Guaranteed  $r_{DS}$  @ 5 V
- Low Turn-On Threshold Voltage
- N-Channel Enhancement Mode

### BENEFITS

- High Speed System Performance
- Low Insertion Loss at High Frequencies
- Low Transfer Signal Loss
- Simple Driver Requirement
- Single Supply Operation

### APPLICATIONS

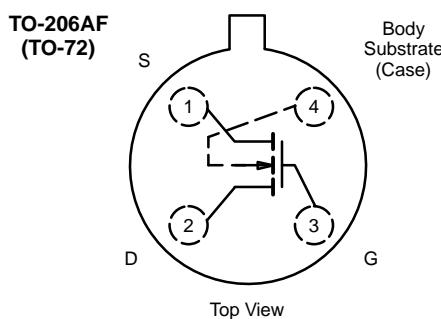
- Fast Analog Switch
- Fast Sample-and-Holds
- Pixel-Rate Switching
- DAC Deglitchers
- High-Speed Driver

### DESCRIPTION

The SD210DE-2/214DE-2 are enhancement-mode MOSFETs designed for high speed low-glitch switching in audio, video, and high-frequency applications. The SD214DE-2 is normally used for  $\pm 10$ -V analog switching. These MOSFETs utilize lateral construction to achieve low capacitance and ultra-fast switching speeds. These MOSFETs do not have a gate protection Zener diode which results in lower gate leakage and  $\pm$  voltage capability from gate to substrate. A poly-silicon gate is featured for manufacturing reliability.

The SD210DE/214DE are available only in the “-2” extended hi-rel flow. The Vishay Siliconix “-2” flow complies with the requirements of MIL-PRF-19500 for JANTX discrete devices.

For similar products see: quad array—SD5000I-2, and Zener protected—SD211DE-2/213DE-2/215DE-2.



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Gate-Drain, Gate-Source Voltage	.....	$\pm 40$ V	Source-Substrate Voltage (SD210DE-2)	.....	15 V
Gate-Substrate Voltage	.....	$\pm 30$ V	(SD214DE-2)	.....	25 V
Drain-Source Voltage (SD210DE-2)	.....	30 V	Drain Current	.....	50 mA
(SD214DE-2)	.....	20 V	Lead Temperature ( $1/16$ " from case for 10 seconds)	.....	300°C
Source-Drain Voltage (SD210DE-2)	.....	10 V	Storage Temperature	.....	-65 to 150°C
(SD214DE-2)	.....	20 V	Operating Junction Temperature	.....	-55 to 125°C
Drain-Substrate Voltage (SD210DE-2)	.....	30 V	Power Dissipation <sup>a</sup>	.....	300 mW
(SD214DE-2)	.....	25 V	Notes:		
			a.	Derate 3 mW/ $^\circ\text{C}$ above 25°C	

Applications Information—See Applications Note AN502

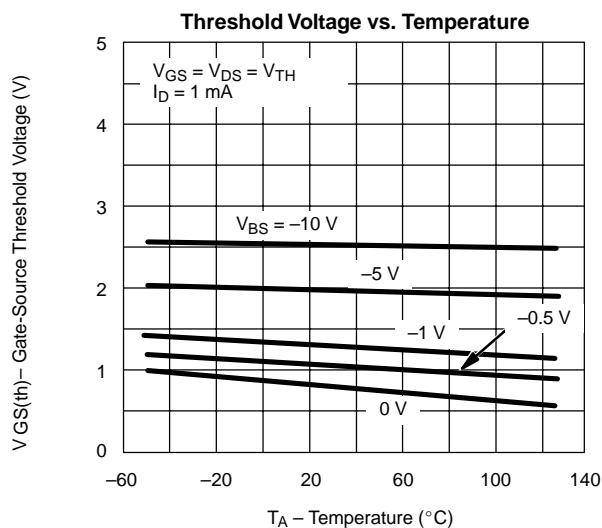
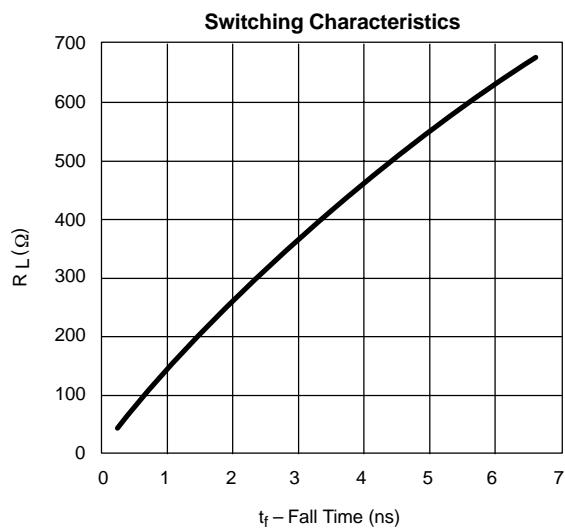
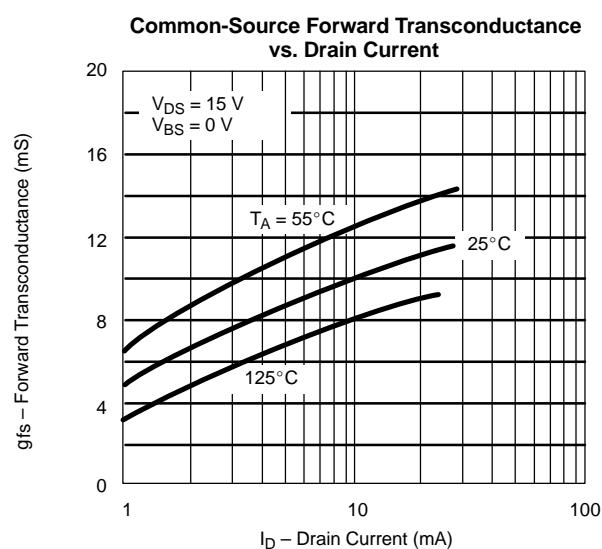
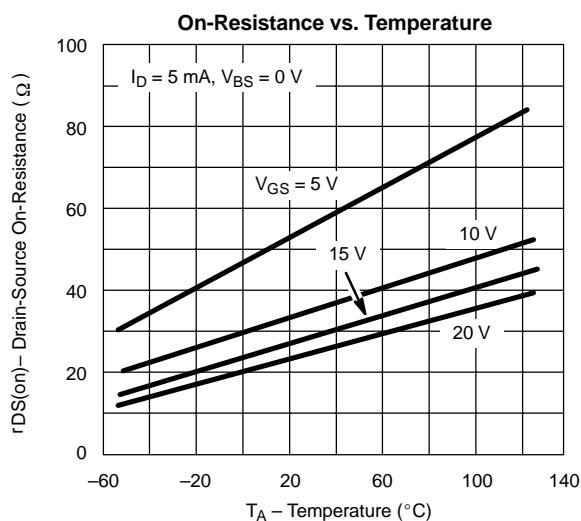
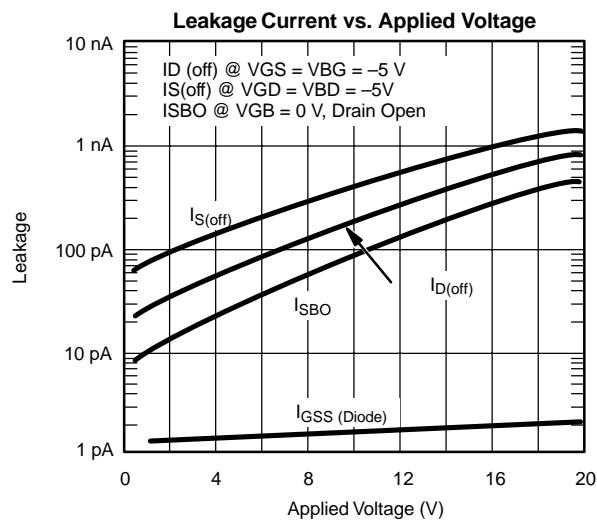
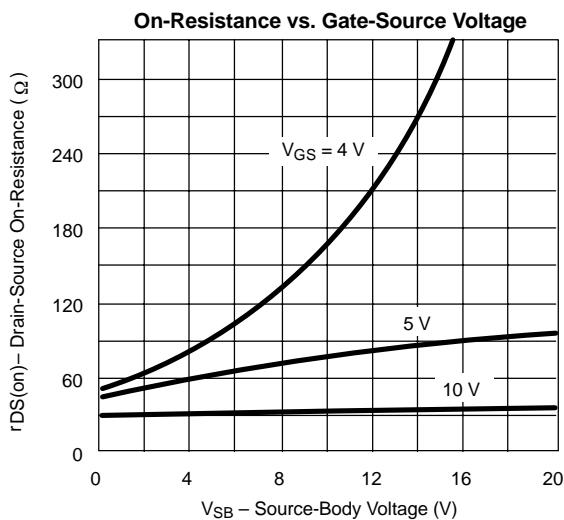
**SPECIFICATIONS<sup>a</sup>**

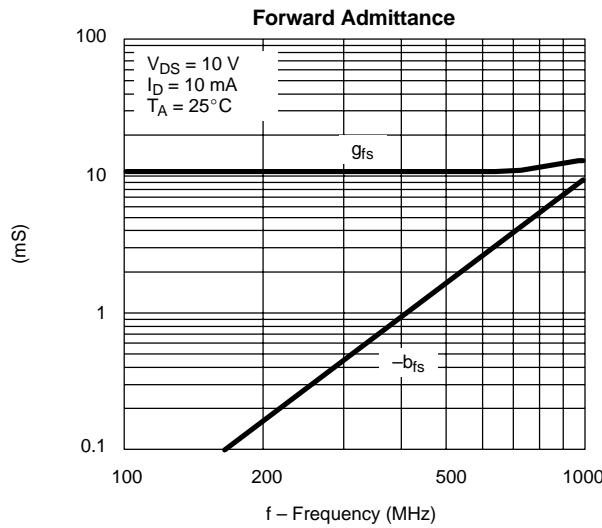
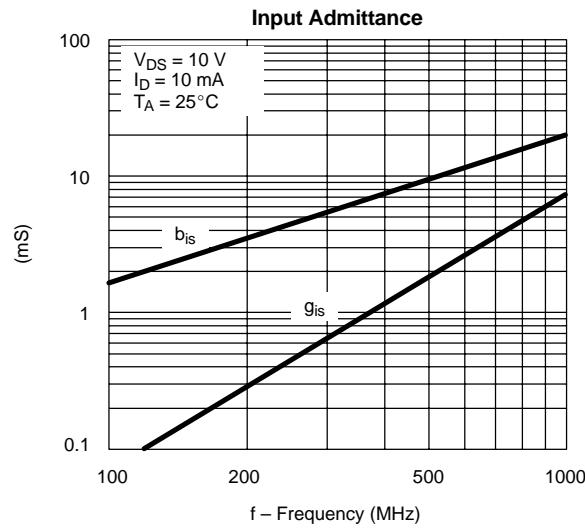
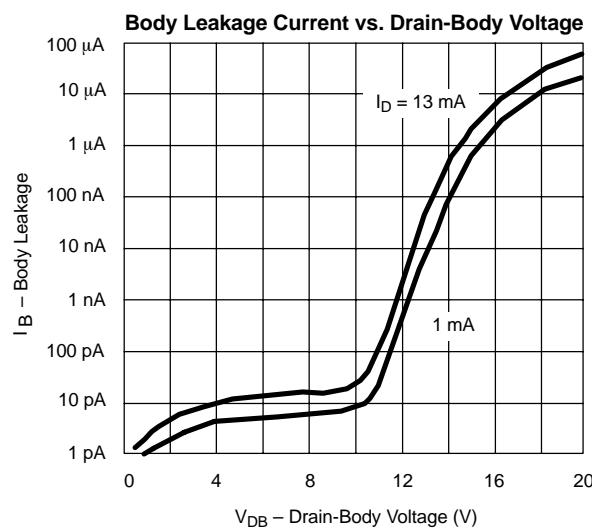
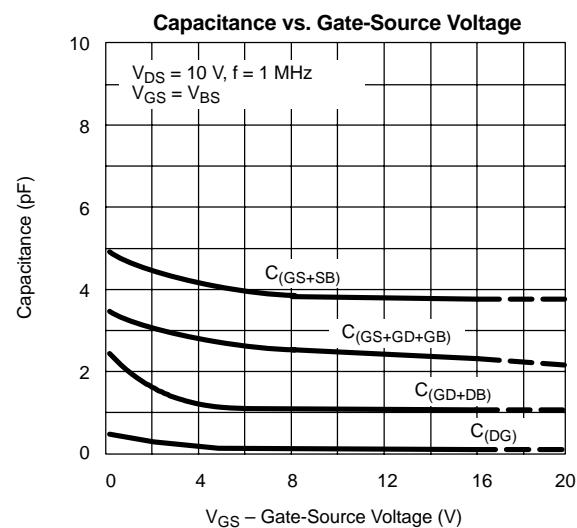
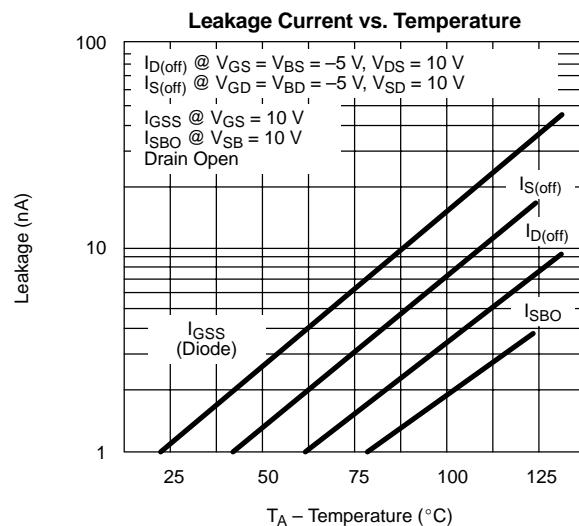
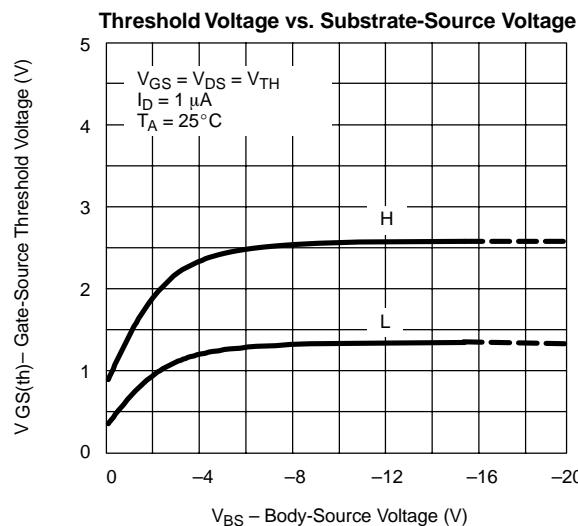
Parameter	Symbol <sup>b</sup>	Test Conditions <sup>b</sup>	Typ <sup>c</sup>	Limits				Unit	
				SD210DE-2		SD214DE-2			
				Min	Max	Min	Max		
<b>Static</b>									
Drain-Source Breakdown Voltage	V <sub>(BR)DS</sub>	V <sub>GS</sub> = V <sub>BS</sub> = 0 V, I <sub>D</sub> = 10 µA	35	30				V	
		V <sub>GS</sub> = V <sub>BS</sub> = -5 V, I <sub>D</sub> = 10 nA	30	10		20			
Source-Drain Breakdown Voltage	V <sub>(BR)SD</sub>	V <sub>GD</sub> = V <sub>BD</sub> = -5 V, I <sub>S</sub> = 10 nA	22	10		20			
Drain-Substrate Breakdown Voltage	V <sub>(BR)DBO</sub>	V <sub>GB</sub> = 0 V, I <sub>D</sub> = 10 nA, Source Open	35	15		25			
Source-Substrate Breakdown Voltage	V <sub>(BR)SBO</sub>	V <sub>GB</sub> = 0 V, I <sub>S</sub> = 10 µA, Drain Open	35	15		25			
Drain-Source Leakage	I <sub>DS(off)</sub>	V <sub>GS</sub> = V <sub>BS</sub> = -5 V	V <sub>DS</sub> = 10 V	0.4		10		nA	
			V <sub>DS</sub> = 20 V	0.9			10		
Source-Drain Leakage	I <sub>SD(off)</sub>	V <sub>GD</sub> = V <sub>BD</sub> = -5 V	V <sub>SD</sub> = 10 V	0.5		10		nA	
			V <sub>SD</sub> = 20 V	0.8			10		
Gate Leakage	I <sub>GBS</sub>	V <sub>DB</sub> = V <sub>SB</sub> = 0 V, V <sub>GB</sub> = ±40 V	0.001		0.1		0.1		
Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1 µA, V <sub>SB</sub> = 0 V	0.8	0.5	1.5	0.1	1.5	V	
Drain-Source On-Resistance	r <sub>DS(on)</sub>	V <sub>SB</sub> = 0 V I <sub>D</sub> = 1 mA	V <sub>GS</sub> = 5 V	58		70		Ω	
			V <sub>GS</sub> = 10 V	38		45			
			V <sub>GS</sub> = 15 V	30					
			V <sub>GS</sub> = 20 V	26					
			V <sub>GS</sub> = 25 V	24					
<b>Dynamic</b>									
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 10 V, V <sub>SB</sub> = 0 V, I <sub>D</sub> = 20 mA f = 1 kHz	11	10		10		mS	
	g <sub>os</sub>		0.9						
Gate Node Capacitance	C <sub>(GS+GD+GB)</sub>	V <sub>DS</sub> = 10 V, f = 1 MHz V <sub>GS</sub> = V <sub>BS</sub> = -15 V	2.5		3.5		3.5	pF	
Drain Node Capacitance	C <sub>(GD+DB)</sub>		1.1		1.5		1.5		
Source Node Capacitance	C <sub>(GS+SB)</sub>		3.7		5.5		5.5		
Reverse Transfer Capacitance	C <sub>rss</sub>		0.2		0.5		0.5		
<b>Switching</b>									
Turn-On Time	t <sub>d(on)</sub>	V <sub>SB</sub> = 0 V, V <sub>IN</sub> 0 to 5 V, R <sub>G</sub> = 25 Ω V <sub>DD</sub> = 5 V, R <sub>L</sub> = 680 Ω	0.5		1		1	ns	
	t <sub>r</sub>		0.6		1		1		
Turn-Off Time	t <sub>d(off)</sub>		2						
	t <sub>f</sub>		6						

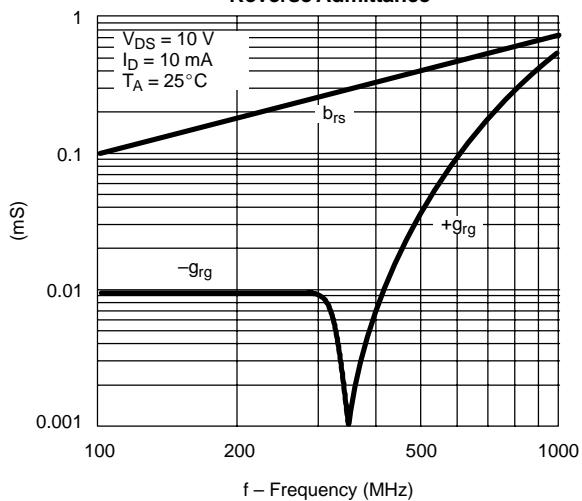
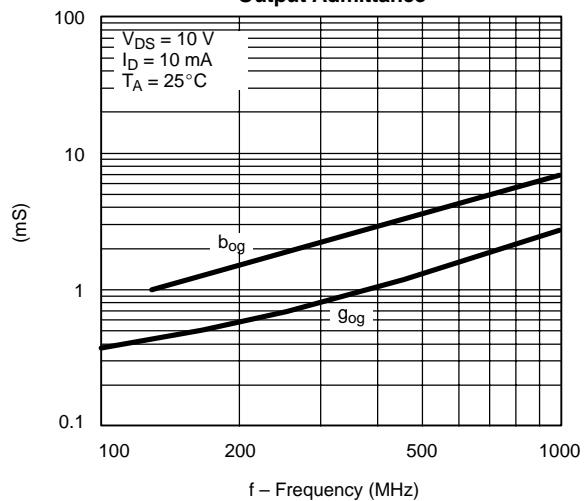
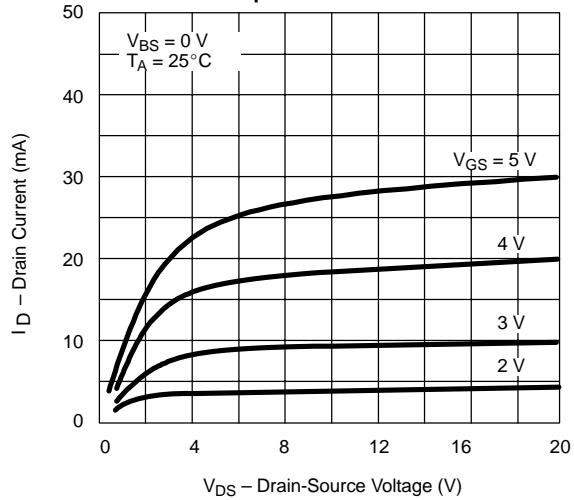
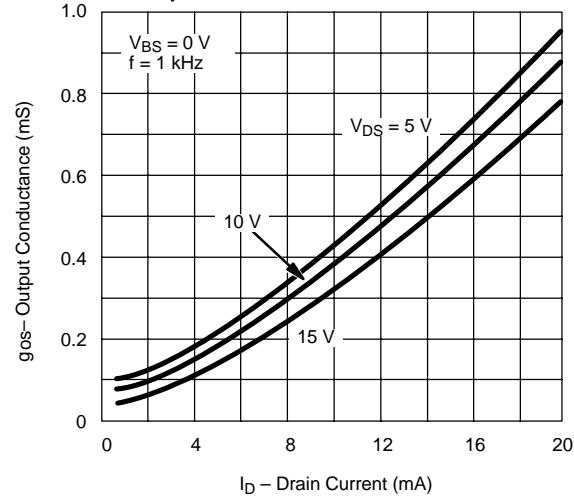
## Notes:

- a. T<sub>A</sub> = 25°C unless otherwise noted.
- b. B is the body (substrate) and V<sub>(BR)</sub> is breakdown.
- c. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.

DMCBB

**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**


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**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**
**Reverse Admittance**

**Output Admittance**

**Output Characteristics**

**Output Conductance vs. Drain Current**

**SWITCHING TIME TEST CIRCUIT**
